

650V 20A Field Stop Trench IGBT

| V _{CES} | 650V |
|-----------------------------|---------------------------|
| I _{C(100°C)} | 10A |
| V _{CE(sat) (Typ.)} | 1.65V@I _C =20A |
| P _D | 39W |

Features

- 1) Low Collector Emitter Saturation Voltage
- 2) Low Switching Loss
- 3) Short Circuit Withstand Time 5µs
- 4) Built in Very Fast & Soft Recovery FRD (RFN - Series)
- 5) Pb free Lead Plating; RoHS Compliant

Applications

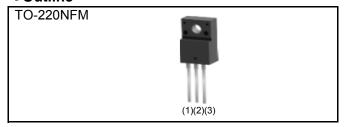
General Inverter

UPS

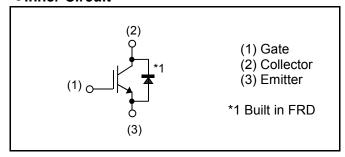
Power Conditioner

Welder

Outline



●Inner Circuit



Packaging Specifications

| | | Packaging | Tube | |
|------|---------------------------|-----------------|------------|--|
| | | Reel Size (mm) | - | |
| | Typo | Tape Width (mm) | - | |
| Туре | Basic Ordering Unit (pcs) | 1,000 | | |
| | | Packing Code | C9 | |
| | | Marking | RGT40TM65D | |

● Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

| Parameter | | Symbol | Value | Unit | |
|--------------------------------|------------------------|-----------------------|-------------|------|--|
| Collector - Emitter Voltage | | V_{CES} | 650 | V | |
| Gate - Emitter Voltage | | V_{GES} | ±30 | V | |
| Collector Current | T _C = 25°C | I _C | 17 | А | |
| Collector Current | T _C = 100°C | I _C | 10 | А | |
| Pulsed Collector Current | | I _{CP} *1 60 | | А | |
| Diode Forward Current | T _C = 25°C | I _F | 22 | А | |
| | T _C = 100°C | I _F | 13 | А | |
| Diode Pulsed Forward Current | | I _{FP} *1 | 60 | А | |
| Power Dissipation | T _C = 25°C | P _D | 39 | W | |
| | T _C = 100°C | P _D | 19 | W | |
| Operating Junction Temperature | | T _j | -40 to +175 | °C | |
| Storage Temperature | | T _{stg} | −55 to +175 | °C | |

^{*1} Pulse width limited by T_{jmax.}

●Thermal Resistance

| Parameter | Symbol | Values | | | Unit |
|--|-------------------|--------|------|------|-------|
| raiametei | | Min. | Тур. | Max. | Offic |
| Thermal Resistance IGBT Junction - Case | $R_{\theta(j-c)}$ | - | ı | 3.82 | °C/W |
| Thermal Resistance Diode Junction - Case | $R_{\theta(j-c)}$ | - | - | 4.47 | °C/W |

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

| Parameter | Symbol | Conditions | Values | | | Unit |
|---|---------------------|--|--------|------|------|-------|
| raiailletei | Syllibol | Conditions | Min. | Тур. | Max. | Offic |
| Collector - Emitter Breakdown Voltage | BV _{CES} | $I_C = 10 \mu A, V_{GE} = 0 V$ | 650 | - | - | V |
| Collector Cut - off Current | I _{CES} | V _{CE} = 650V, V _{GE} = 0V | 1 | - | 10 | μΑ |
| Gate - Emitter Leakage Current | I _{GES} | $V_{GE} = \pm 30V, V_{CE} = 0V$ | 1 | - | ±200 | nA |
| Gate - Emitter Threshold Voltage | $V_{\text{GE(th)}}$ | $V_{CE} = 5V, I_{C} = 13.3 \text{mA}$ | 5.0 | 6.0 | 7.0 | V |
| Collector - Emitter Saturation Voltage | | I _C = 20A, V _{GE} = 15V | | | | |
| | $V_{CE(sat)}$ | T _j = 25°C | - | 1.65 | 2.1 | V |
| | | T _j = 175°C | - | 2.15 | - | |

●IGBT Electrical Characteristics (at T_j = 25°C unless otherwise specified)

| Darameter | Symbol | Conditions | | Unit | | | |
|----------------------------------|---------------------|--|-------------|------|------|-------|--|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Ullit | |
| Input Capacitance | C _{ies} | V _{CE} = 30V | - | 1070 | - | | |
| Output Capacitance | C _{oes} | V _{GE} = 0V | - | 45 | - | pF | |
| Reverse Transfer Capacitance | C _{res} | f = 1MHz | - | 18 | - | | |
| Total Gate Charge | Qg | V _{CE} = 300V | - | 40 | - | | |
| Gate - Emitter Charge | Q_ge | I _C = 20A | - | 9 | - | nC | |
| Gate - Collector Charge | Q_{gc} | V _{GE} = 15V | - | 15 | - | | |
| Turn - on Delay Time | t _{d(on)} | I _C = 20A, V _{CC} = 400V | - | 22 | - | | |
| Rise Time | t _r | $V_{GE} = 15V, R_G = 10\Omega$ | - | 27 | - | ns | |
| Turn - off Delay Time | t _{d(off)} | T _j = 25°C | - | 75 | - | | |
| Fall Time | t _f | Inductive Load | - | 60 | - | | |
| Turn - on Delay Time | t _{d(on)} | I _C = 20A, V _{CC} = 400V | - | 22 | - | | |
| Rise Time | t _r | $V_{GE} = 15V, R_{G} = 10\Omega$ | - | 29 | - | 20 | |
| Turn - off Delay Time | t _{d(off)} | T _j = 175°C | - | 84 | - | ns | |
| Fall Time | t _f | Inductive Load | - | 120 | - | | |
| | | I _C = 60A, V _{CC} = 520V | | | | | |
| Reverse Bias Safe Operating Area | RBSOA | $V_P = 650V, V_{GE} = 15V$ | FULL SQUARE | | | - | |
| | | $R_G = 50\Omega, T_j = 175^{\circ}C$ | | | | | |
| | | $V_{CC} \le 360V$ | | | | | |
| Short Circuit Withstand Time | t_{sc} | V _{GE} = 15V | 5 | - | - | μs | |
| | | T _j = 25°C | | | | | |

●FRD Electrical Characteristics (at T_j = 25°C unless otherwise specified)

| Parameter | Symbol | Conditions | Values | | | Linit |
|--|-----------------|--|--------|--------------|----------|-------|
| | | | Min. | Тур. | Max. | Unit |
| Diode Forward Voltage | V _F | $I_F = 20A$ $T_j = 25^{\circ}C$ $T_j = 175^{\circ}C$ | - | 1.45 1.25 | 1.9 - | V |
| Diode Reverse Recovery Time | t _{rr} | $I_F = 20A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 25^{\circ}C$ | - | 58 | - | ns |
| Diode Peak Reverse Recovery Current | I _{rr} | | - | 6.3 | - | Α |
| Diode Reverse Recovery Charge | Q_{rr} | | - | 0.20 | - | μC |
| Diode Reverse Recovery Time | t _{rr} | I _F = 20A | - | 256 | - | ns |
| Diode Peak Reverse Recovery Current | I _{rr} | $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 175^{\circ}C$ | - | 10.4 | - | А |
| Diode Reverse Recovery Charge | Q_{rr} | | - | 1.35 | - | μC |

•Electrical Characteristic Curves

Fig.1 Power Dissipation vs. Case Temperature

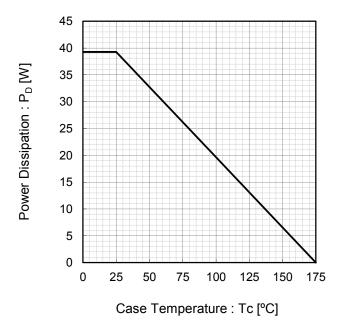


Fig.2 Collector Current vs. Case Temperature

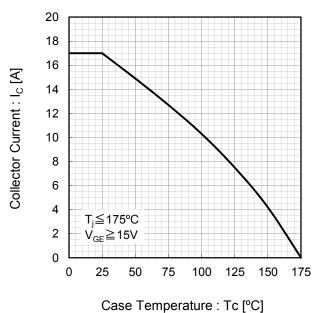
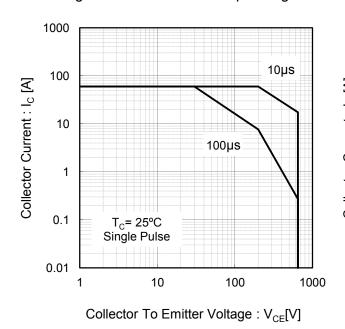


Fig.3 Forward Bias Safe Operating Area



Collector Current : I_C [A]

80
60
40
20
T_j≤175°C
V_{GE}=15V
0
0 200 400 600 800

Fig.4 Reverse Bias Safe Operating Area

Collector To Emitter Voltage : $V_{CE}[V]$

• Electrical Characteristic Curves

Fig.5 Typical Output Characteristics

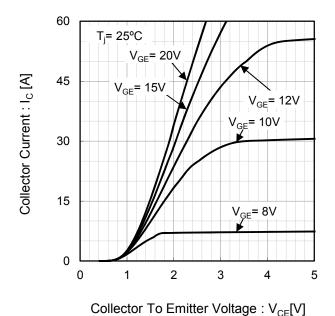
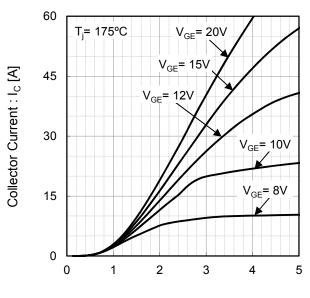


Fig.6 Typical Output Characteristics



Collector To Emitter Voltage : $V_{CE}[V]$

Fig.7 Typical Transfer Characteristics

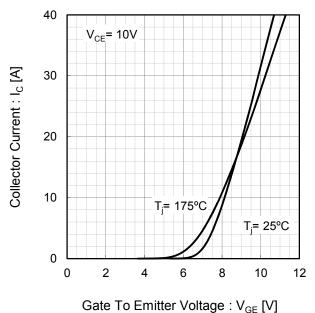
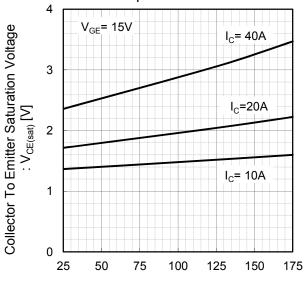


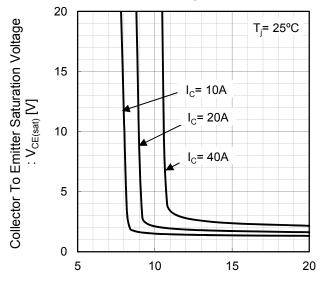
Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature



Junction Temperature : T_i [°C]

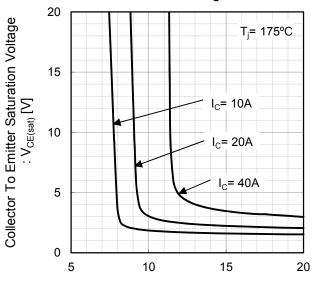
Electrical Characteristic Curves

Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage : V_{GE} [V]

Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage



Gate To Emitter Voltage : V_{GE} [V]

Fig.11 Typical Switching Time vs. Collector Current

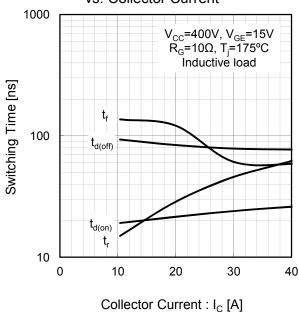
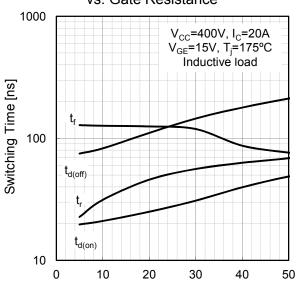


Fig.12 Typical Switching Time vs. Gate Resistance



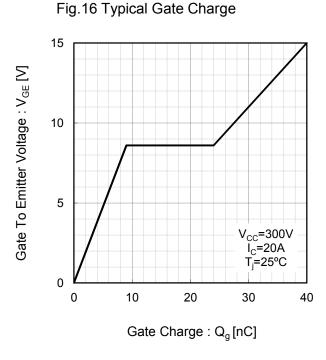
• Electrical Characteristic Curves

Fig.13 Typical Switching Energy Losses vs. Collector Current 10 Switching Energy Losses [mJ] 1 $\mathsf{E}_{\mathsf{off}}$ E_{on} 0.1 V_{CC} =400V, V_{GE} =15V R_{G} =10 Ω , T_{j} =175°C Inductive load 0.01 0 10 20 30 40 Collector Current : I_C [A]

vs. Gate Resistance 10 Switching Energy Losses [mJ] 1 E_{off} E_{on} 0.1 V_{CC}=400V, I_C=20A V_{GE}=15V, T_j=175°C Inductive load 0.01 10 20 30 40 50 0 Gate Resistance : $R_G[\Omega]$

Fig.14 Typical Switching Energy Losses

Fig.15 Typical Capacitance vs. Collector To Emitter Voltage 10000 Cies 1000 Capacitance [pF] Coes 100 Cres 10 f=1MHz V_{GE}=0V T,=25°C 0.01 0.1 1 10 100 Collector To Emitter Voltage : V_{CE}[V]



•Electrical Characteristic Curves

Fig.17 Typical Diode Forward Current vs. Forward Voltage 60 45 Forward Current : I_F [A] 30 15 T_i= 175°C T_i= 25°C 0 0.5 1.5 2 2.5 3 0

vs. Forward Current 400 V_{CC}=400V di_F/dt=200A/μs Reverse Recovery Time : t_{rr} [ns] Inductive load 300 T_i= 175°C 200 100 T_i= 25°C 0 20 30 50 0 10 40 Forward Current : I_F [A]

Fig.18 Typical Diode Reverse Recovery Time

Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current

Forward Voltage : V_F[V]

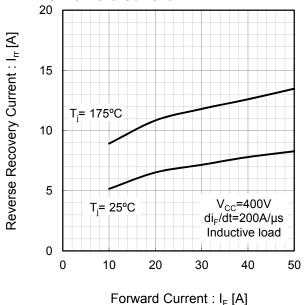
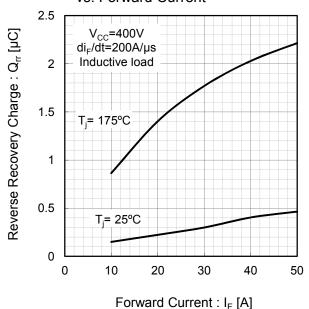


Fig.20 Typical Diode Reverse Recovery Charge vs. Forward Current



•Electrical Characteristic Curves

Fig.21 IGBT Transient Thermal Impedance

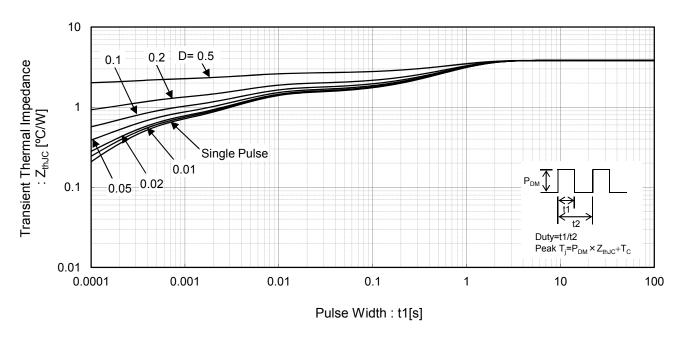
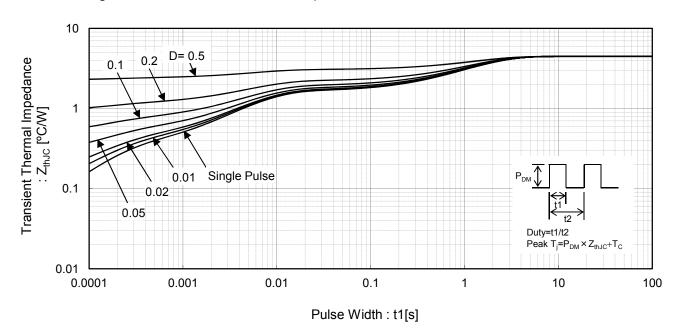


Fig.22 Diode Transient Thermal Impedance



●Inductive Load Switching Circuit and Waveform

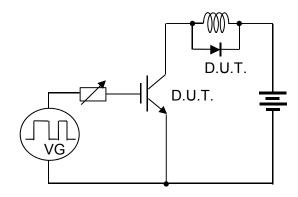


Fig.23 Inductive Load Circuit

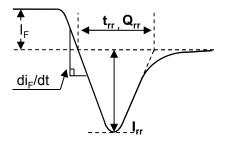


Fig.25 Diode Reverce Recovery Waveform

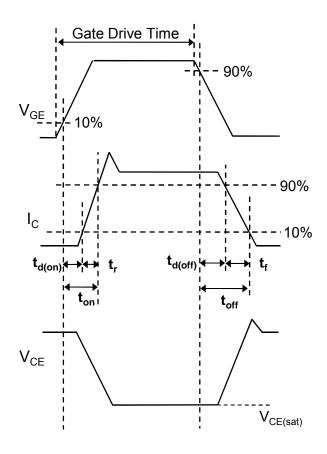


Fig.24 Inductive Load Waveform

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